



Device Material Content

5555 NE Moore Ct. Hillsboro OR 97124 custreq@latticesemi.com					Package Code: LFG672		Assembly: ASEK Size (mm): 27x27 Lead pitch (mm): 1 MSL: 4 Reflow max (°C): 250	
April, 2025	Package: Total Device Weight		672 fCBGA 2225.61 Milligrams		Products: LFCPNX-100			
	% of Total Pkg. Wt.	Weight (mg)	% of Total Pkg. Wt.	Weight (mg)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	4.824%	107.362	4.824%	107.362	Silicon chips	7440-21-3	100.00%	
Underfill	0.359%	8.000	0.108% 0.009% 0.027% 0.205% 0.002% 0.009%	2.400 0.200 0.600 4.560 0.040 0.200	Bisphenol F type liquid epoxy resin Bisphenol A type liquid epoxy resin Amine type hardener Silicon dioxide Carbon Black Additives	9003-36-5 25068-38-6 - 60676-86-0 1333-86-4 -	30.00% 2.50% 7.50% 57.00% 0.50% 2.50%	Namics ASE-UA59
Solder Balls	25.238%	561.700	24.342% 0.757% 0.126% 0.013%	541.760 16.851 2.809 0.281	Tin (Sn) Silver (Ag) Copper (Cu) Nickel (Ni)	7440-31-5 7440-22-4 7440-50-8 7440-02-0	96.45% 3.00% 0.50% 0.05%	PMT Sn96.45/Ag3.0/Cu0.5/Ni0.05
Substrate Core	53.358%	1187.541	5.601% 15.919% 15.919% 15.919%	124.659 354.294 354.294 354.294	copper Glass Cloth Silica Vitreous Thermosetting (Resin and other filler)	7440-50-8 65997-17-3 60676-86-0 Trade secret	10.50% 29.83% 29.83% 29.83%	Core: MCLE705G
	3.660%	81.466	0.275% 0.275% 0.055% 0.022% 0.005% 0.005% 0.002% 0.002% 1.446% 1.574%	6.110 6.110 1.222 0.489 0.122 0.041 0.041 32.179 35.030	Bisphenol A epoxy resin Bisphenol F epoxy resin Coal tar naphtha Cyclohexanone Toluene Methyl ethyl ketone Naphthalene Trimethylbenzene Silicon dioxide Others	25068-38-6 9003-36-5 64742-94-5 108-94-1 108-88-3 78-93-3 91-20-3 25551-13-7 7631-86-9 Trade Secret	7.50% 7.50% 1.50% 0.60% 0.15% 0.150% 0.050% 0.050% 39.500% 43.000%	ABF : GX92R
	0.021%	0.473	0.020% 0.001% 0.0001%	0.456 0.014 0.002	Tin Silver Copper	7440-31-5 7440-22-4 7440-50-8	96.500% 3.000% 0.50%	Solder Ball :SAC305
	1.494%	33.242	0.224% 0.149% 0.224% 0.149% 0.075% 0.037% 0.007% 0.007% 0.007% 0.538% 0.075%	4.986 3.324 4.986 3.324 1.662 0.831 0.166 0.166 0.166 11.967 1.662	Barium sulfate Silica, vitreous Diethylene glycol monoethyl ether acetate 1-Butanol, 3-methoxy-3-methyl-, acetate Solvent naphtha(petroleum), heavy aromatic 1-Propanone, 2-methyl-1-[4-(methylthio)phenyl]-2-(4-morpholinyl)- Melamine Butylated hydroxytoluene Naphthalene Modified epoxy resin Additive	7727-43-7 60676-86-0 112-15-2 103429-90-9 64742-94-5 71868-10-5 108-78-1 128-37-0 91-20-3 Trade Secret Trade Secret	15.00% 10.00% 15.00% 10.00% 5.00% 2.50% 0.50% 0.50% 0.50% 36.00% 5.00%	Soldermask: Showa Denko SR7300GR-B
Plating	10.881%	242.159	10.839% 0.041%	241.245 0.914	Plating Cu Plating Tin	7440-50-8 7440-31-5	99.62% 0.38%	
Repassivation Polyimide	0.025%	0.557	0.014% 0.001% 0.0001% 0.010%	0.303 0.030 0.003 0.221	N-Methyl-2-pyrrolidone Proprietary Monomer Methanol Non regulated ingredients	872-50-4 - 67-56-1 -	54.46% 5.45% 0.50% 39.60%	HD4000E (HD4100)
RDL	0.116%	2.573	0.001% 0.114%	0.031 2.542	Titanium Copper	7440-32-6 7440-50-8	1.19% 98.79%	
UBM	0.007%	0.152	0.001% 0.005%	0.031 0.121	Titanium Copper	7440-32-6 7440-50-8	20.20% 79.80%	
Bump	0.017%	0.384	0.010% 0.000% 0.001% 0.007%	0.215 0.004 0.013 0.152	Tin (Sn) Silver (Ag) Nickel (Ni) Copper (Cu)	7440-31-5 7440-22-4 7440-02-0 7758-98-7	56.02% 1.03% 3.32% 39.63%	
Note: 100.000% 2225.61 100.000% 2225.61								
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